

AMENDMENTS TO THE SPECIFICATION

Please amend the specification at page 12, line 1 to line 7 to read as follows:

~~Figure 2A~~ Section A of Figure 2 illustrates a sensor package wherein two horizontal, 1-dimensional, sensor circuit components are mounted separately in space on the PCB, with only one of the two sensor circuit components serving as a support for the vertical sensor circuit component 103. ~~Figure 2B~~ Section B of Figure 2 illustrates a sensor package wherein the two horizontal, 1-dimensional, sensor circuit components 204 are in contact, conductively or non-conductively attached, with both serving as a support for the vertical sensor circuit component 103.

Please amend the specification at page 14, line 20 to page 15, line 1 to read as follows:

Such exemplary electrical connections are represented by wire bonds or TAB bonds 105 between the horizontal sensor circuit component 102, 204 and the PCB 101 in section A of Figure 3 ~~Figure 3 (A)~~, solder joints 105 between the vertical sensor circuit component 103 and the PCB 101 in sections A and C of Figure 3 ~~Figure 3 (A) and (C)~~, and stud bumps encased in conductive epoxy 105 between the vertical sensor circuit component 103 and the PCB 101 in section B of Figure 3 ~~Figure 3 (B)~~.

Please amend the specification at page 16, line 22 to page 17, line 1 to read as follows:

Similarly, for embodiments such as that illustrated in section B of Figure 2 ~~Figure 2(B)~~, any of the sensor components 103, 204 can be in direct electrical communication with any other sensor component to which it is abutted.

Please amend the specification at page 18, line 5 to line 13 to read as follows:

Similarly, a sensor component fixture 107 can be utilized with embodiments such as that illustrated in section B of Figure 2 ~~Figure 2(B)~~, wherein all sensor components 103, 204 are in direct electrical or non-electrical communication. As with Figures 4 and 5, the methods of forming electrical interconnections 105 outlined above are preferably utilized separately but can be utilized simultaneously.

Figure 7 is a schematic diagram of an exemplary vertical die chip-on-board sensor package where an array of I/O pads 702 is arranged on the second face of a vertical sensor circuit component (analogous to section C of Figure 3 ~~Figure 3(C)~~), in this exemplary case orthogonal to the sensitive direction of the vertical sensor circuit component.

Please amend the abstract to the specification at page 32, line 1 to line 5 to read as follows:

Methods and apparatus for vertical die chip-on-board sensor packages ~~are provided. Such vertical die chip-on-board sensor packages~~ can comprise a vertical sensor circuit component comprising a first face, a second face, a bottom edge, a top edge, two side edges, input/output (I/O) pads and at least one sensitive direction wherein the I/O pads are arranged near the bottom edge.